



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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PRODUCT NUMBER

87610-YXXLF

RoHS COMPATIBLE, SEE NOTE 7

PLATING

2 = 0.76µm GOLD/GXT
(PdNi WITH GOLD FLASH) ON CONTACT AREA
2µm MIN MATTE TIN ON TAIL

UNDERPLATE : 1.27µm Ni MIN

NOTES:

- 1 - HOUSING MAT'L : GLASS FILLED THERMOPLASTIC. UL94V-0 COLOR: BLUE
- 2 - PIN MATERIAL : PHOSPHOR BRONZE
- 3 - PRODUCT PACKAGED IN TUBES.
- 4 - TO DETERMINE DIMENSIONS :
N = NUMBER OF POSITIONS PER ROW
EXAMPLE : 8 POS N x 2.54 = 20.32mm
- 5 - NO RIGHT POLARIZATION FOR POS 04, 06, 08.
- 6 - NO LEFT POLARIZATION FOR POS 04, 06, 08, 14.
- 7 - RETENTION LEGS IN THE CENTER OF THE CONNECTOR.
- 8 - RoHS COMPATIBLE PRODUCT SPECIFICATIONS

a - PLATING:

- "LF" MEANS THE PRODUCT IS LEAD-FREE,
2µm MINIMUM MATTE TIN OVER 1.27µm
MINIMUM NICKEL UNDERPLATE.

b - MANUFACTURING PROCESS COMPATIBILITY

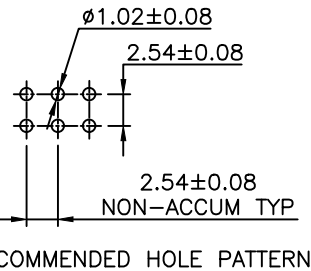
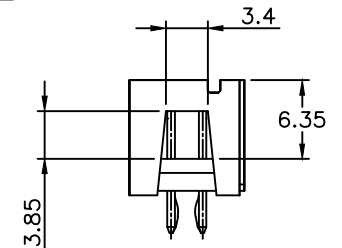
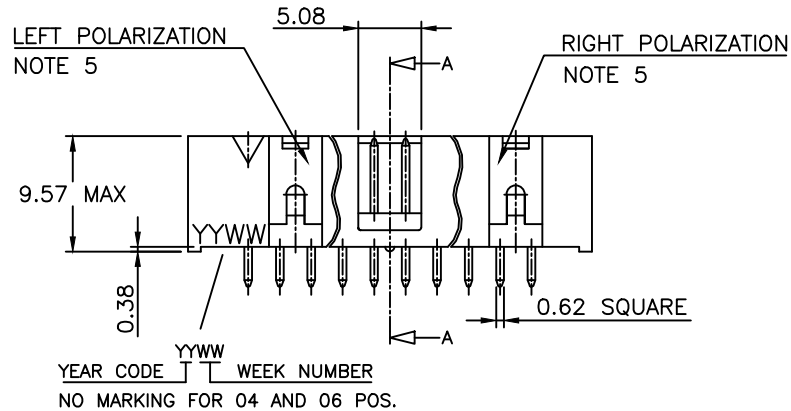
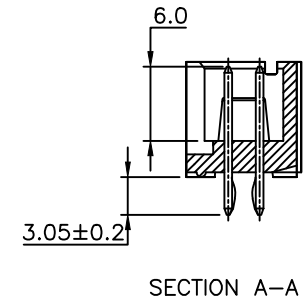
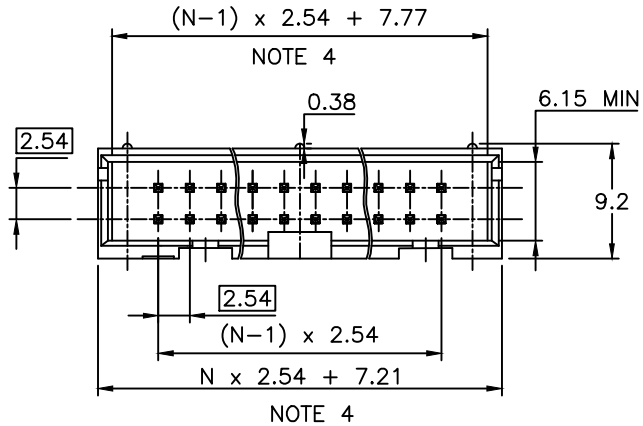
- THE HOUSING WILL WITHSTAND EXPOSURE TO
260°C ±5°C SOLDER BATH TEMPERATURE FOR
5 SECONDS IN A WAVE SOLDER APPLICATION
WITH A 1.6mm MIN THICK CIRCUIT BOARD.

c - LABELLING:

- MEETS PACKAGING SPECS AS PER GS-14-920

d - LEGAL STATEMENT: SEE GS-47-0004

TOTAL NUMBER OF POSITIONS	
06	26
08	34
10	40
14	44
16	50
18	60
20	64



mat'l. code SEE NOTES		surface ISO 1302	tolerance ISO 406 ISO 1101	projection	product family QUICKIE	
ltr	ecn no	dr	date	tolerances unless otherwise specified	title	
K	F07-0198	LMU	07.05.30	angles	SHR.LP.HEADER STR RETENTION LEGS	
L	F08-0146	YOV	08.04.11	Linear		
M	B-19071	LMU	14.10.15			
N	B-19094	LMU	14.10.16	dr	scale 2.5:1	
H	F04-0389	JCO	04.12.22	DLE	01.01.24	
J	F06-0229	LMU	06.07.18	enrg	JCO	04.12.20
sheet index	revision sheet			appd	JCO	04.12.22



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